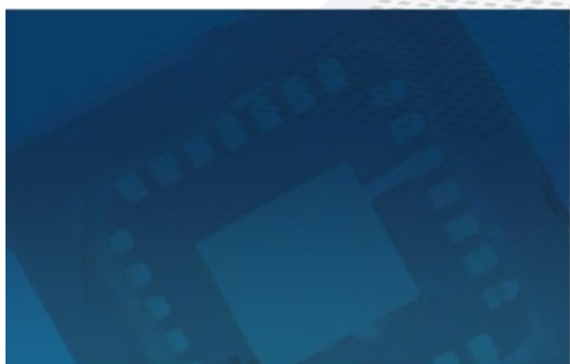
EVERWIDE

Everwide Chemical Co., Ltd.

C-MOS模組

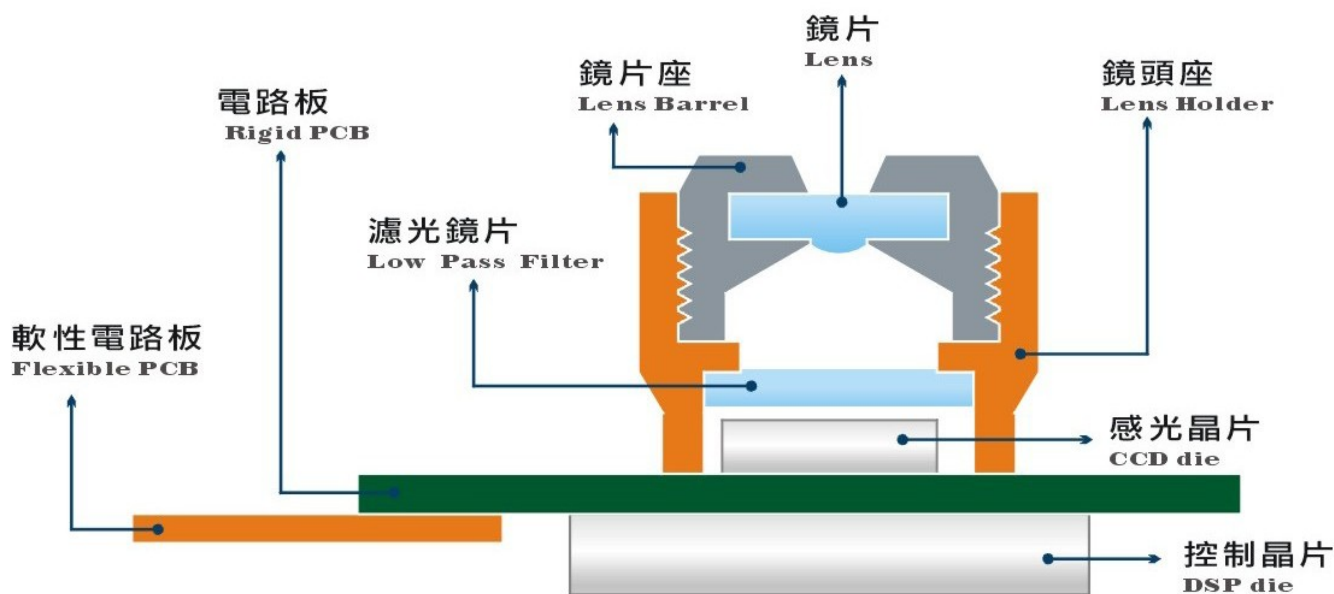
接著應用型錄

C-MOS Module Bonding Application



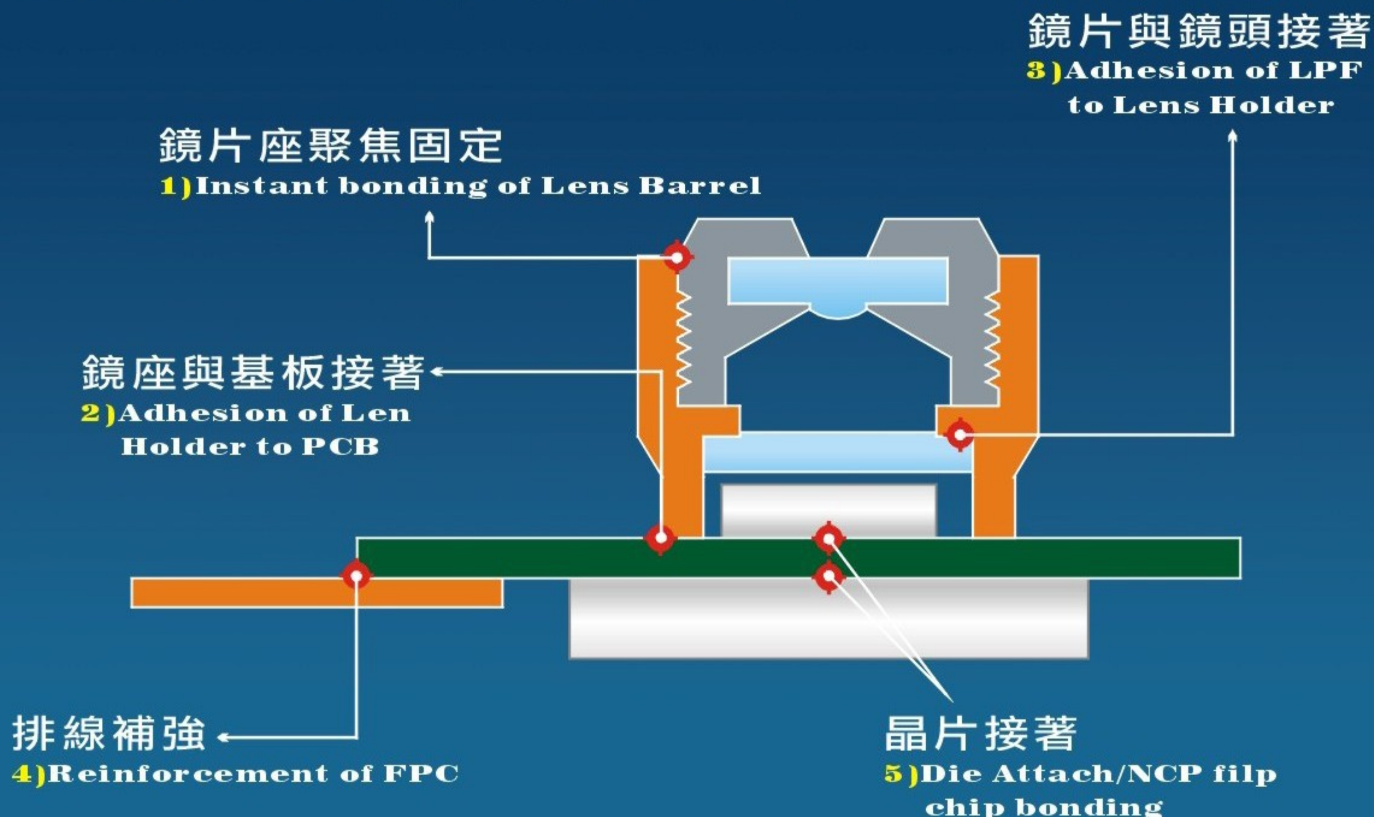
C-MOS模組架構圖

Module structure



C-MOS模組接著應用

Module bonding application

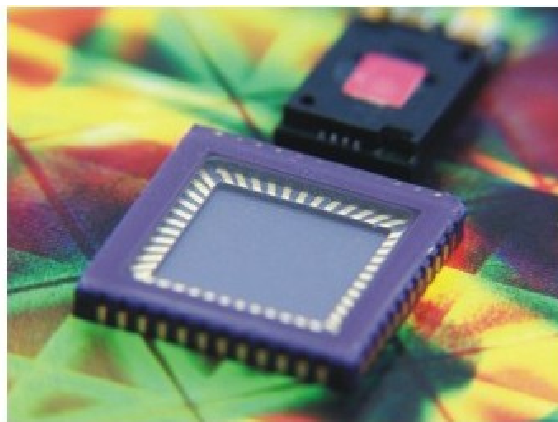


C-MOS晶圓封裝

C-MOS Optical Die encapsulate

- **FR4,FR5,BT,陶瓷…等基板與光學玻璃接著**
  FR4, FR5,BT,Ceramic Etc. substrate bonding with Optical glass
  - 使用UV+熱烤之陽離子型環氧樹脂
    UV+ heat cure cationic epoxy
  - 高TI值作業性佳, 收縮率小
    High Ti value easy working, low shrinkage
  - 含水率低，防水性極佳
    Low water content, excellent water resistance
  - 耐260℃無鉛Reflow 3次
    It can pass 260℃* 2~3min* 3 times

產品編號 Product Item.	黏度值 cps Viscosity	固化參數 Curing Parameter	Tg by TMA	硬度 Hardness Shore D	體積收縮率 Volume Shrinkage	吸水率 95℃*24hrs
JB093	30000~ 50000	3000mj/cm^2+ 130℃*30min	108℃	85	3%	2.4%
FP569	20000	2000mj/cm^2	89℃	78	5.2%	2.8%



C-MOS模組接著

C-MOS Module bonding Application

應用一: 鏡片支架與鏡頭座在對焦後快速固定

Application1: Fast fixture after focus in Lens holder with lens

- 高黏度,高TI值UV膠

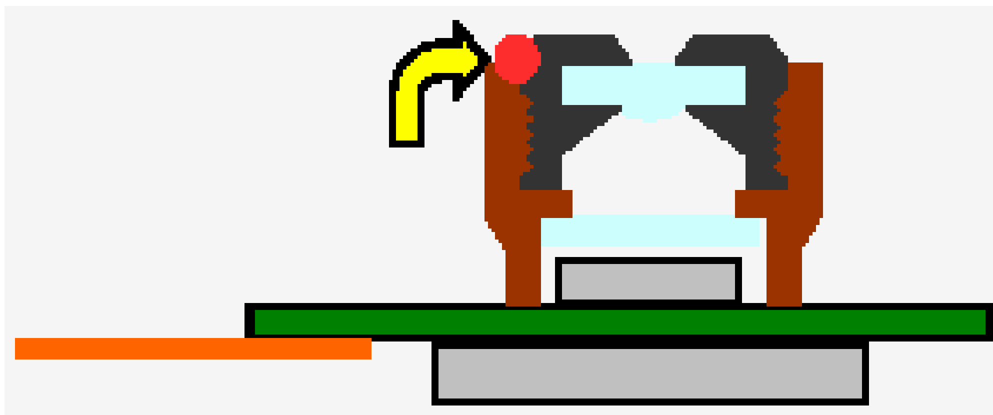
  High viscosity, High Ti value UV adhesive
- 超快速固化(點光源2秒)

  Fast cure by spot-light UV equipment
- 膠材表面乾燥性佳

  Well surface dry
- 對鏡頭座多種類塑膠材質接著性適中可重工

  Bonding with lens holder of multi-plastic, easy rework

產品編號 Product Item.	黏度值 Viscosity cps	固化參數 Curing parameter	硬度 Hardness Shore D	使用溫度 Temp. range ℃	吸水率 Water absorption 25℃*168hrs
GN537	10000	1500~2000mj/cm^2	72	-40~100	2.2%
GN559	12000	1500~2000mj/cm^2	72	-40~100	2.2%
GN560	15000	2000mj/cm^2	70	-20~100	2.2%



C-MOS模組接著

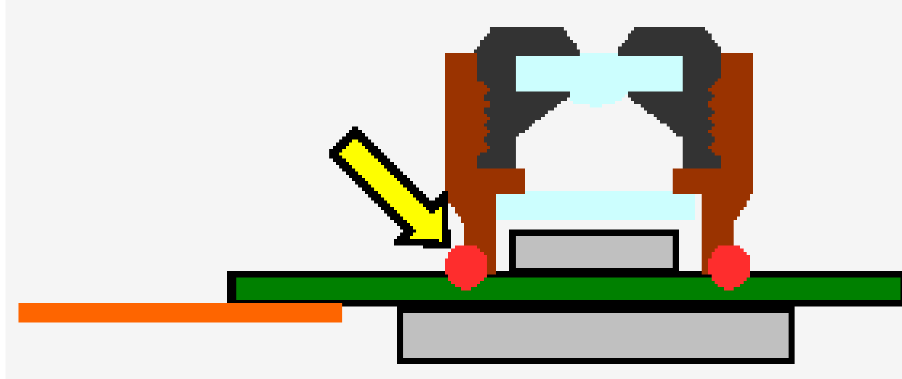
C-MOS Module bonding Application

應用二: 鏡頭座與FR4 ,Glass or FPC基材接著

Application2: Lens holder bonding with FR4, Glass, FPC substrate

- 超低溫60~80℃熱烤型環氧樹脂
  Low temp. curing 60~80℃ thermal cure epoxy
- 對鏡頭座多種類塑膠材質接著性佳
  Bonding with lens holder of multi-plastic
- 膠材室溫下可工作時間長達48hr
  Working life 48hrs in RT
- 黑色不透光
  Black color , prevent light transmission.
- 防水性佳
  Good water resistance

產品編號 Product Item.	黏度值 Viscosity, cps	固化參數 Curing Parameter	硬度 Hardness Shore D	玻璃轉換溫度 Tg	使用溫度 Temp. Range ℃	吸水率 Water absorption 100℃*2hrs
GE106	45000	60℃*60min 80℃*45min	82	>80℃	-40~100	1.8%
GE137	45000	60℃*60min 80℃*45min	80	>80℃	-40~100	1.7%
GE152	6000	60℃*60min 80℃*45min	80	>80℃	-40~100	1.9%



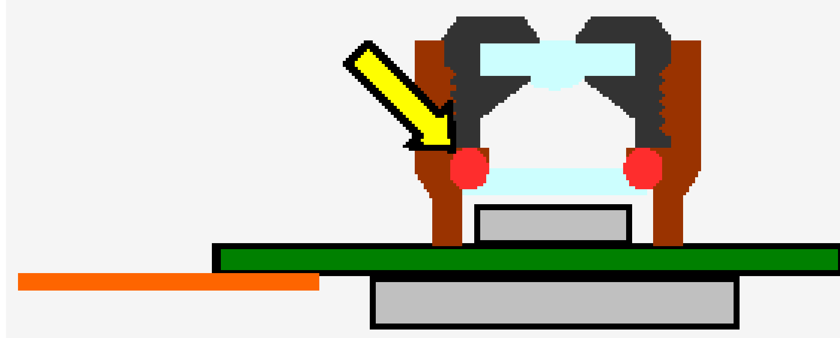
C-MOS模組接著
C-MOS Module bonding Application

應用三: 濾光鏡片與鏡頭座接著

Application3: IR filter Lens bonding with lens holder

- 可見光波長反應UV膠
  Reaction by visible light
- 固化能量低
  Low UV energy curing
- 對鏡頭座多種類塑膠材質接著性佳
  Bonding with lens holder of multi-plastic
- 接著強度高於1.5kgf
  Bonding strength higher 1.5kgf
- 防水性佳
  Excellent water resistance

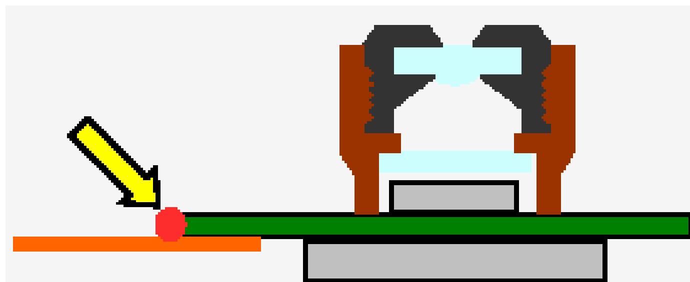
產品編號 Product Item.	黏度值 Viscosity ,cps	固化參數 curing parameter	硬度 Hardness Shore D	水煮boiling 100 ℃*24hrs	使用溫度 Temp. range ℃	吸水率 Water absorption 25℃*168hrs
FP574	10000c	1500~3000j /cm²	50	Pass	-40~100	2.0%
FP254	8000	1500~3000 mj/cm²	57	Pass	'-40~100	2.5%
GN435	5500	1500~3000 mj/cm²	57	Pass	-40~100	2.2%



C-MOS模組接著
C-MOS Module bonding Application

- **應用四: FPC軟性電路板補強**
  Application4: Flexible reinforcement
  - 快速硬化UV膠
    Fast cure UV adhesive
  - 對FPC及PCB接著性佳
    Good bonding strength FPC+PCB(FR4, FR5,BT)
  - 接著強度高於1.5kg每公分寬
    Bonding strength higher 1.5kg-cm
  - 可撓性佳>120°
    Flexible> 120°

產品編號 product Item	黏度值 Viscosity cps	固化參數 Curing parameter	硬度 Hardness Shore D	水煮boiling 100 ℃*24hrs	使用溫度 Temp. range ℃	吸水率 Water absorption 25℃*168hrs
9323	3600	1500~3000 mj/cm²	D56	Pass	-40~100	3.0%
FG139	13000	1200~1500 mj/cm²	A40~50	Pass	-40~100	2.5%
9330	28000	1200~1500 mj/cm²	D68	Pass	-40~100	3.3%



C-MOS模組接著
C-MOS Module bonding Application

應用五: 晶片固定
Application: Die bonding

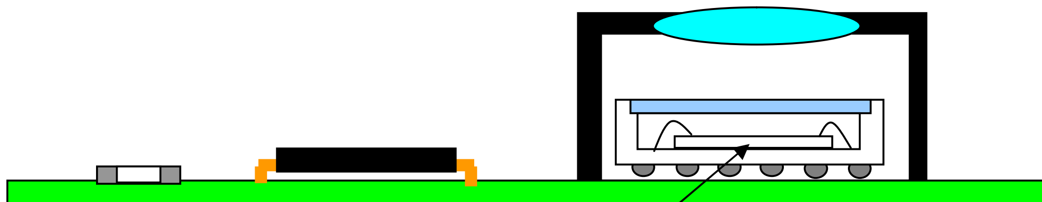
- 低溫80~100℃*10min快速固化

  Low Temp. 80~100℃* 10min fast cure
- 對PCB及其他基材接著性佳

  Good bonding strength with PCB
- 接著推力強度高於3.5kg

  Bonding strength higher 3.5kg

產品編號 Product Item	黏度值 Viscosity cps	固化參數 Curing Parameter	硬度 Hardness Shore D	水煮Boiling 100 ℃*24hrs	使用溫度 Temp. Range ℃	吸水率 Water absorption 100℃*2hrs
GE053	280000	100 ℃ *5min	80	Pass	-40~100	1.6%
GE084	250000	100 ℃ *10min	82	Pass	-40~100	1.8%



晶片接著Die Attach

C-MOS模組接著

C-MOS Module bonding Application

應用六: 晶片底部填充

Application: Die bonding

- 低溫120℃*20min快速固化

  Low Temp. 120℃* 20min fast cure

- 對小間隙200um以下流速快

  Fast flow speed below 200um gap

產品編號 Product Item	黏度值 Viscosity cps	固化參數 Curing Parameter	硬度 Hardness Shore D	流動速率 10*10mm, sec	使用溫度 Temp. Range ℃	吸水率 Water absorption 97℃*90min
JB462	4200	120 ℃ *20min	40	Slow	‘-40~100	1.2%
JB526	2500	120 ℃ *20min	40	Medium	-40~100	1.2%
JB526-1	2000	100 ℃ *40min	42	Fast	-40~100	1.1%
JB589	3000	120 ℃ *20min	55	Fast	-40~100	1.81%
JB590	2500	120 ℃ *20min	80	Fast	-40~100	3.45%